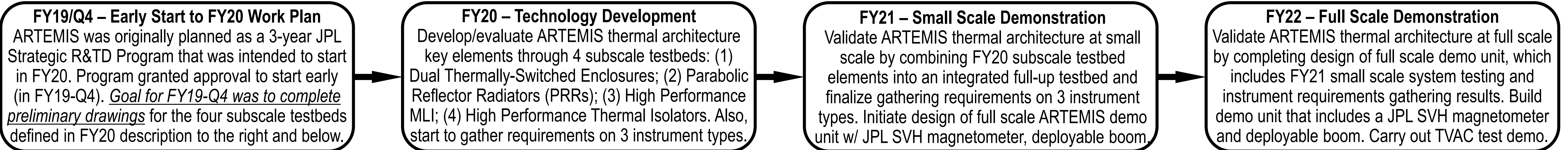


Thermal Technology Development for the ARTEMIS Initiative

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Program: Strategic R&TD

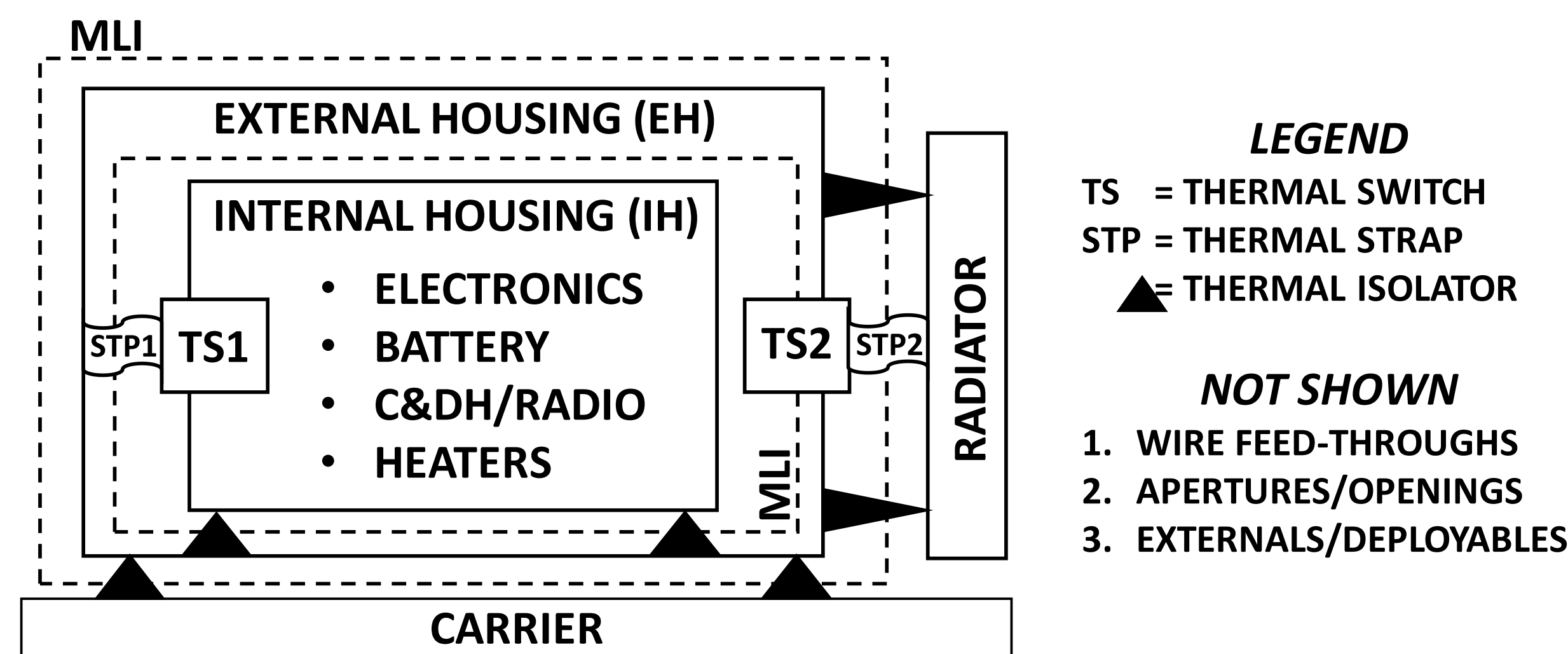
OBJECTIVE: Develop an *autonomous lunar night survivable thermal architecture* without radioisotopes to enhance JPL's lunar instrument implementation capabilities with a science focus on *magnetometers, seismometers, and IR spectrometers*.



ARTEMIS Technology Development Focus Areas and Key Measurable Metrics (KMM)

- Dual Thermally-Switched Enclosure**
KMM → Lunar Heat Loss Flux < 5 W/m²
- Affordable Parabolic Reflector Radiator**
KMM → Sink Temp on Lunar Surface < 280 K
- High Performance Multi-Layer Insulation**
KMM → Effective Emissivity < 0.01
- High Performance Thermal Isolator**
KMM → Conductance < 0.001 W/K
- Science Instrument Requirements**
KMM → 50% defined by FY20, 100% by FY21

ARTEMIS AUTONOMOUS THERMAL ARCHITECTURE



HOW IT WORKS: During Lunar Day, heat from instruments conducted along the thermal path IH → TS1 → STP1 → EH → TS2 → STP2 → RAD with TS1 and TS2 both ON. As Lunar Night ensures, TS2, TS1 turn OFF autonomously at 273 K, drastically reducing heat loss. Thermal Switches are JPL Reverse-Operation Differential Thermal Expansion (DTE) Thermal Switches (5 W/K ON, 0.002 W/K OFF, 2500:1 ON/OFF). To validate architecture, series of 4 TESTBED subtasks in concert with an INSTRUMENT THERMAL NEEDS subtask planned for FY20.

Subtask	Concept	Design	CAD	Drawings	KMM Validation
1 → Develop subscale assembly of ARTEMIS architecture; design and build testbed to show performance.		SIZING (IH, EH, SHROUD) - 127, 254, 381 mm x 6 mm Al cubes - 305 mm x 305 mm x 3 mm Al radiator LUNAR NIGHT SIMULATION - TCP = 90 K, T _{IH} > 240 K (survival heater) LUNAR DAY SIMULATION - TCP = 280 K (PRR assumed), Q _{IH} = 5-8 W THERMAL SWITCH - JPL Rev.-Op. DTE Design-2 (Utem 1000/Alum) THERMAL STRAP - Graphite foil based, 2 W/K (Thermotive)		1. INTERNAL HOUSING (IH) - 20019541 2. EXTERNAL HOUSING (EH) - 20019542 3. LUNAR SHROUD (LS) - 20019543 4. THERMAL SWITCH - 20019547 → 20019551 5. THERMAL STRAP, RADIATOR - 20019546, 20019554 6. OVERALL ASSEMBLY - 20019545	Heat loss flux < 5 W/m ² , means 127 mm IH cube will require < 0.5 W to stay warm in the cold case. With conventional ε* = 0.02 MLI, T _{IH} must be > 253 K.
2 → Develop design and fabrication method for low cost PRRs; design, build testbed to show performance.		SIZING (IR PLATE, PRR, LS) - IR PLATE (381 mm into page x 508 mm) - PRR (N=10, D / H / W = 127 / 12.7 / 6.35 mm) - LS (approx. 500 mm x 600 mm x 200 mm) LUNAR NIGHT SIMULATION - NOT REQUIRED LUNAR DAY SIMULATION - TCP = 90-280 K - TIRP = 373 K - Q _{PRR} = 0-2 W - Q _{IRP} = 200 W (approx.)		1. PRR 10-CELL RADIATOR ARRAY - 20019931 2. PRR 10-CELL REFLECTOR ARRAY - 20019932 3. PRR TESTBED: IR PLATE - 20019934 4. PRR TESTBED: LUNAR SHROUD - 20019935 → 20019938 5. PRR TESTBED: OVERALL ASSEMBLY - 20019939	Rad. sink temp < 280 K is applicable when lunar shroud temperature is set to 90 K. With lunar shroud at 280 K, radiative sink temp will exceed 280 K.
3 → Develop design and fabrication method for low ε* MLI; design and build testbed to show performance.		SIZING (DEMO MODEL, TESTBED) - INNER FRAME, HSG (IF, IH) 87 mm, 127 mm - OUTER FRM, HSG (EF, EH) 165 mm, 384 mm KEVLAR CABLES - CORNER CABLE 62 mm x 8 - PERIPHERAL CABLE #1 99 mm x 12 (inner) - PERIPHERAL CABLE #2 111 mm x 12 - PERIPHERAL CABLE #3 123 mm x 12 - PERIPHERAL CABLE #4 135 mm x 12 - PERIPHERAL CABLE #5 147 mm x 12 (outer)		1. SPACERLESS MLI (S-MLI) DEMO MODEL - 20019555 2. S-MLI TESTBED: IH + KEVLAR BRKTS - 20019561*, 20019562* 3. S-MLI TESTBED: EH + KEVLAR BRKTS - 20019563*, 20019564* 4. S-MLI TESTBED: LS + KEVLAR BRKTS - 20019565*, 20019566* 5. S-MLI TESTBED: OVERALL ASSEMBLY - 20019560* <small>* Drawing number assigned, drawing incomplete</small>	MLI ε* < 0.01 will require test setup w/ just a few wires to minimize parasitic heat gains/leaks so that the relation ε* = Q/(T _i ⁴ - T _o ⁴) is the sole governing eqn.
4 → Develop design and fabrication method for low G isolators; design, build testbed to show performance.		SIZING (STRUCTURAL FEM) - SUPPORT FOR 10 KG INSTRUMENT PKG. - FOUR ISOLATORS PER INSTRUMENT PKG. - PACKAGE DIMENSIONS 300 x 200 x 150 mm		1. POLYMER FLEXURE ISOLATOR - 20019553-1 2. POLYMER KEVLAR CABLE ISOLATOR - 20019951* 3. ISOLATOR TESTBED: COLD SHROUD - 20019952* 4. ISOLATOR TESTBED: Q-METER - 20019953* 5. ISOLATOR TESTBED: OVERALL ASSY - 20019954* <small>* Drawing number assigned, drawing incomplete</small>	Isolator G < 0.001 W/K will require test setup with Q-meter that minimizes parasitic heat gains/leaks so that G = Q/DT is the sole governing equation.

Instrument Implementation			DTE Thermal Switching		Future Challenges	
TYPE	CHALLENGES	CANDIDATES	At 300 K, ROD Stretched for High DISC-CYL "ON" Force At < 273 K, CYL Differentially Contracts Causing "OFF" Gap		Reverse-Operation DTE Thermal Switch Prototypes and Exaggerated Gap on LN2-Exposed Demo Unit	
MAGNETOMETER	External Boom Boom Deployment External Fiber Optics	SVH SI-C Others			BATTERIES RADIO/COMM C&DH GIMBAL	→ Packaging Enough for Overnight Ops/Survival → Internals + Antenna for Carrier Independence
SEISMOMETER	Rigid Link to Carrier High Data Rate High Duty Cycle	SP UMS Others			INSTRUMENT SUITES	→ IR Spectrometers May Need 2-Axis Gimbal → Multi-Instrument Capability Sought by NASA
IR SPECTROMETER	High Power (Cryocooler) High Data Rate Apertures, External Gimbal	UCIS-Moon SILVIR Others			THERMAL STORAGE LOOP HEAT PIPE PLANETARY USE	→ Use 100 K Nighttime Temps to Eliminate CCs → Combo Unit with Switch for 20000:1 ON/OFF → Extended Stroke Thermal Switch (see Demo Unit)

ARTEMIS ARchitecture for Thermal Enclosure of Moon Instrument Suites